

LINEAR TECHNOLOGY MATERIALS DECLARATION

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(Engineering Calculation)

PDIP

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TOTAL MASS (g) : 0.500529

COMPONENT MATERIAL	VENDOR/ INDUSTRY NAMES	CONSTITUENT NAME	CAS NUMBER	CONSTITUENT MASS (g)	CONSTITUENT (PPM) OF MATERIAL	CONSTITUENT (PPM) OF TOTAL PKG.		
Active Device	Linear Technology	Silicon (Si)	7440-21-3	0.003683	1000000	7358.2109375		
Die Coat	Dow Corning	Silicone	69430-27-9	0.000882	1000000	1762.13476562		
Lead Frame	Cu	Copper (Cu)	7440-50-8	0.149760	975000	299203.25		
		Iron (Fe)	7439-89-6	0.003686	24000	7364.20410156		
		Phosphorus (P)	7723-14-0	0.000046	300	91.9027175903		
		Zinc (Zn)	7440-66-6	0.000108	700	215.771591187		
		Nickel (Ni)	7440-02-0	0.000000	0	0		
		Silicon (Si)	7440-21-3	0.000000	0	0		
		Magnesium (Mg)	7439-95-4	0.000000	0	0		
		Tin (Sn)	7440-31-5	0.000000	0	0		
Lead Frame Total:				0.153600	1000000	306875.15625		
Plating	PMI	Exter. Plating Pb	7439-92-1	0.000000	0	0		
		Exter. Plating Sn	7440-31-5	0.012410	1000000	24794.3339844		
		External Plating Total:				0.012410	1000000	24794.3339844
		Inter. Plating Ni	7440-02-0	0.000000	0	0		
		Inter. Plating Ag	7440-22-4	0.001228	1000000	2453.40283203		
Internal Plating Total:				0.001228	1000000	2453.40283203		
Die Attach	ELECTRICALLY CONDUCTIVE ADHESIVE	Silver (Ag)	7440-22-4	0.001042	750000	2081.79638672		
		Tin (Sn)	7440-31-5	0.000000	0	0		
		Lead (Pb)	7439-92-1	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.000000	0	0		
		Indium (In)	7440-74-6	0.000000	0	0		
		Metal Oxide		0.000000	0	0		
		Antimony (Sb)	7440-36-0	0.000000	0	0		
		Resin (EP)		0.000347	250000	693.266113281		
Die Attach Total:				0.001389	1000000	2775.06225586		
Encapsulation	FILLED EPOXY RESIN	Resin (EP)		0.078520	240000	156873.9375		
		Bromine (Br)	40039-93-8	0.003272	10000	6537.07958984		
		Silica (SiO2)	60676-86-0	0.235561	720000	470623.78125		
		Antimony Trioxide (Sb2O3)	1309-64-4	0.009815	30000	19609.2421875		
		Metal Hydroxide		0.000000	0	0		
		Carbon Black (C)	1333-86-4	0.000000	0	0		
		Encapsulation Total:				0.327168	1000000	653644
Bond Wire Estimated	AFW/TANAKA/ Kn	Gold (Au)	7440-57-5	0.000169	1000000	337.642578125		
					TOTAL MASS (g) :	0.500529		